PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMC6035IM/NOPB	Obsolete	Production	SOIC (D) | 8	-	-	Call TI	Call TI	-40 to 85	LMC60 35IM
LMC6035IMM/NOPB	Active	Production	VSSOP (DGK) | 8	1000 | SMALL T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	A06B
LMC6035IMM/NOPB.A	Active	Production	VSSOP (DGK) | 8	1000 | SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	A06B
LMC6035IMM/NOPB.B	Active	Production	VSSOP (DGK) | 8	1000 | SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	A06B
LMC6035IMMX/NOPB	Active	Production	VSSOP (DGK) | 8	3500 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	A06B
LMC6035IMMX/NOPB.A	Active	Production	VSSOP (DGK) | 8	3500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	A06B
LMC6035IMMX/NOPB.B	Active	Production	VSSOP (DGK) | 8	3500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	A06B
LMC6035IMX/NOPB	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	LMC60 35IM
LMC6035IMX/NOPB.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC60 35IM
LMC6035IMX/NOPB.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC60 35IM
LMC6035ITL/NOPB	Active	Production	DSBGA (YZR) | 8	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 80
LMC6035ITL/NOPB.A	Active	Production	DSBGA (YZR) | 8	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 80
LMC6035ITL/NOPB.B	Active	Production	DSBGA (YZR) | 8	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 80
LMC6035ITLX/NOPB	Active	Production	DSBGA (YZR) | 8	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 80
LMC6035ITLX/NOPB.A	Active	Production	DSBGA (YZR) | 8	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 80
LMC6035ITLX/NOPB.B	Active	Production	DSBGA (YZR) | 8	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 80
LMC6035YAFR	Active	Production	DSBGA (YAF) | 8	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3I6H
LMC6035YAFR.A	Active	Production	DSBGA (YAF) | 8	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3I6H
LMC6036IM/NOPB	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	-40 to 85	LMC6036IM
LMC6036IMTX/NOPB	Active	Production	TSSOP (PW) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6036I, LMC603) 6IMT

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMC6036IMTX/NOPB.A	Active	Production	TSSOP (PW) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6036I, LMC603) 6IMT
LMC6036IMTX/NOPB.B	Active	Production	TSSOP (PW) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6036I, LMC603) 6IMT
LMC6036IMX/NOPB	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC6036IM
LMC6036IMX/NOPB.A	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC6036IM
LMC6036IMX/NOPB.B	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC6036IM

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF LMC6035 :

- Automotive : LMC6035-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects